

Calibration of the TimePix chip & pad enlargement chips

5th RD51 collaboration meeting



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I Experimental setup

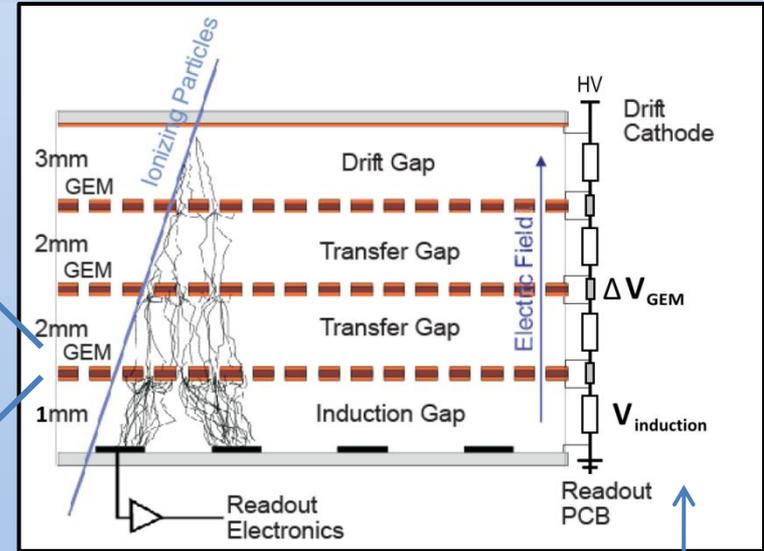
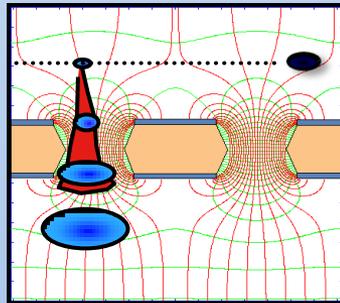
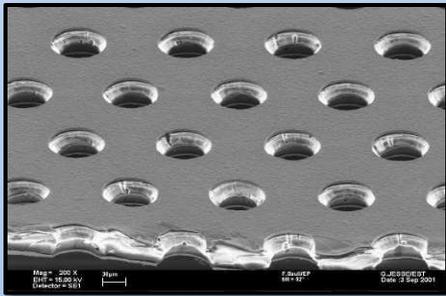
II Comparison of pixel sizes

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IV Charge calibration

V New test chamber

GEM Setup



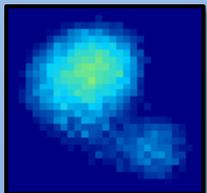
resistive voltage divider:
same potential difference (ΔV_{GEM}) per GEM

GEM+TimePix

charge is spread over *several pixels* (>50)

Consequences

- few e^- per channel (strong diffusion effects within the GEM-stack)
→ high gas gain necessary for detection of *minimal ionizing particles*

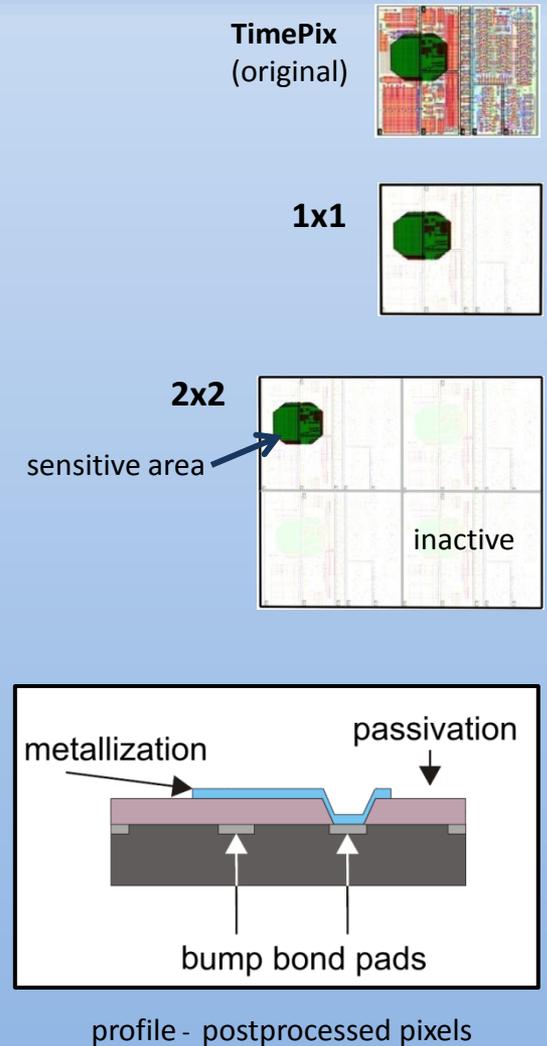
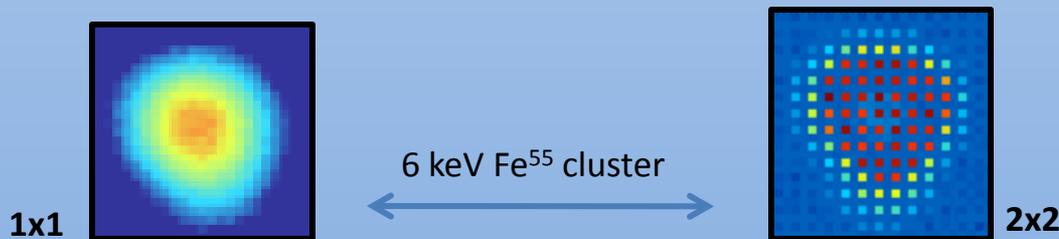


Postprocessed chips (IZM)

- **1x1:** metallization extended from $\approx 20 \times 20 \mu\text{m}^2$ to $\approx 50 \times 50 \mu\text{m}^2$
- **2x2:** 3 of 4 pixels passivated, then metallized pixel size $105 \times 105 \mu\text{m}^2$

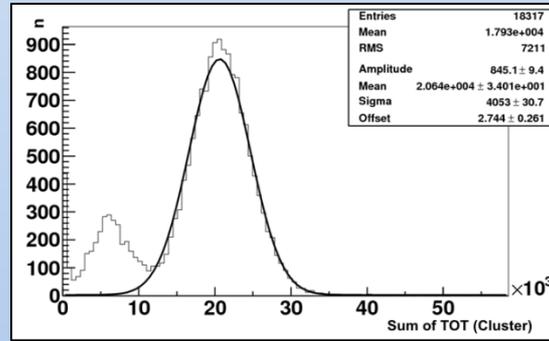
Motivation: enlarged pixels

- more charge per pixel
→ higher probability of detection
- less gas amplification needed → fewer positive ions
- optimization of spatial resolution vs. pixel size



Setup

- gas: HeCO₂/ Fe55 (6 keV photons)
- 1x1 and 2x2 with similar thresholds



Example: ArCO₂

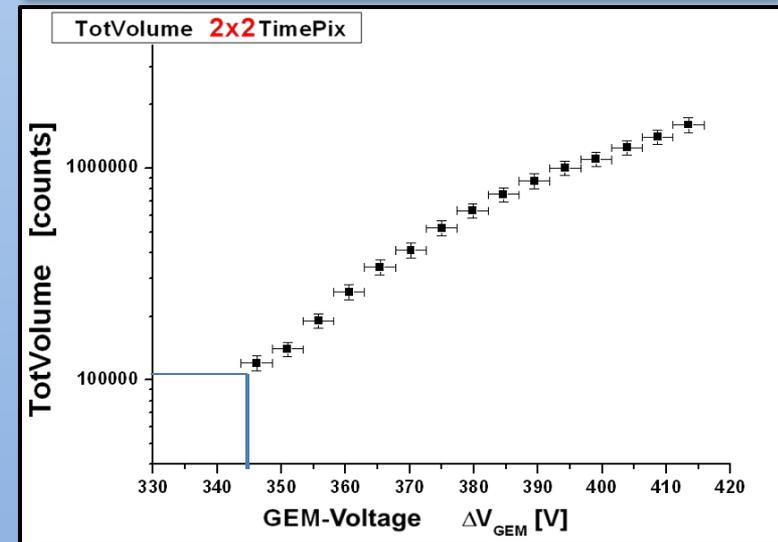
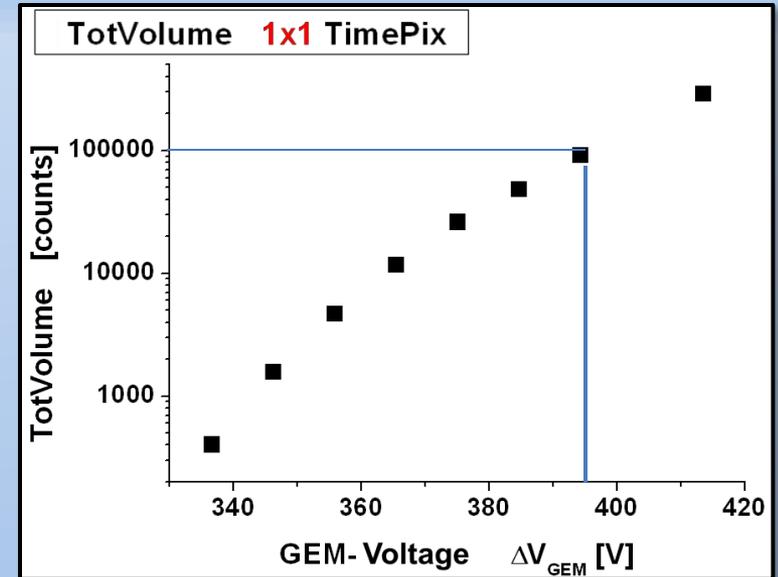
Procedure

- find clusters
- sum up the *TOT* values of the pixels (TOT - counts clock cycles above a chosen threshold)
- fit gauss (peak)
- take mean = *TOTVolume*

Comparison

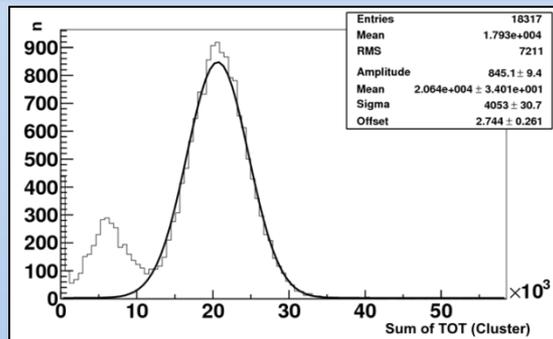
with pixel enlargement:
→ less gas gain needed

$$(\Delta V_{\text{GEM}}) \approx 50 \text{ V}$$



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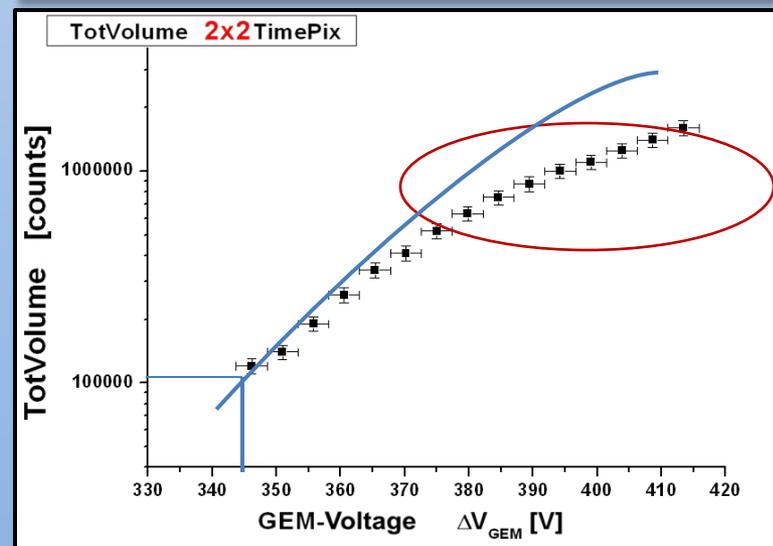
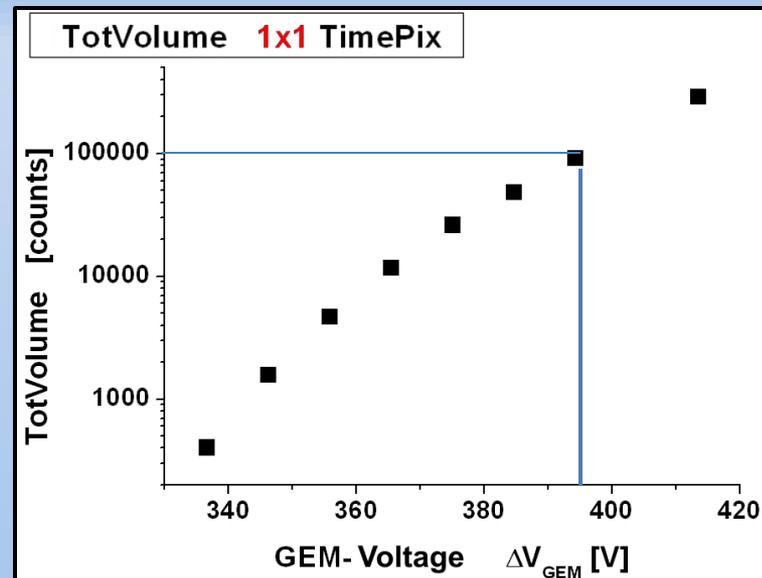
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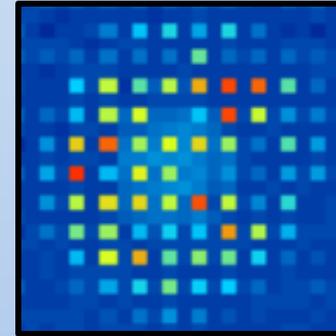


TOT-drop

insulation of the passivation not sufficient

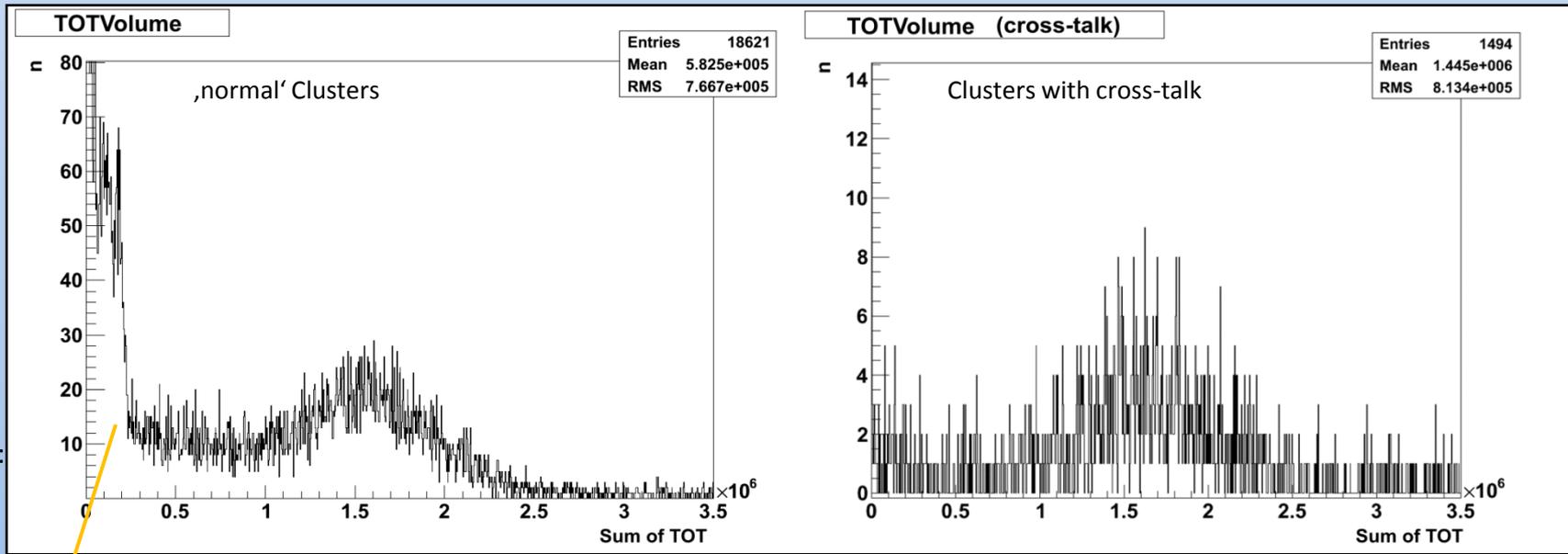
→ charge on masked pixels

Does cross-talk depend on the **deposited charge**?



Fe55-source
Volt./GEM: 385V
2x2 all pixels

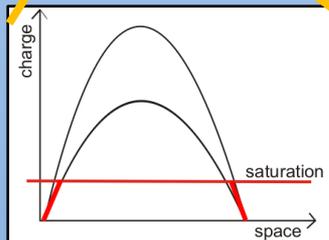
TOT-drop



2x2
Fe55 source
GEM voltage:
415 V



just noise



profile of a saturated cluster

Procedure

- find clusters (min size 6 pixels)
- select clusters: with and without cross-talk

← **problem:** ,saturation' of charge at cluster center

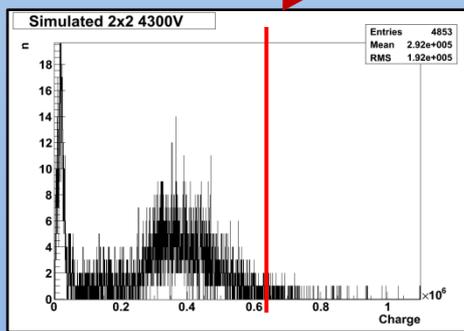
Analysis

pixels are saturated → no **real** charge information

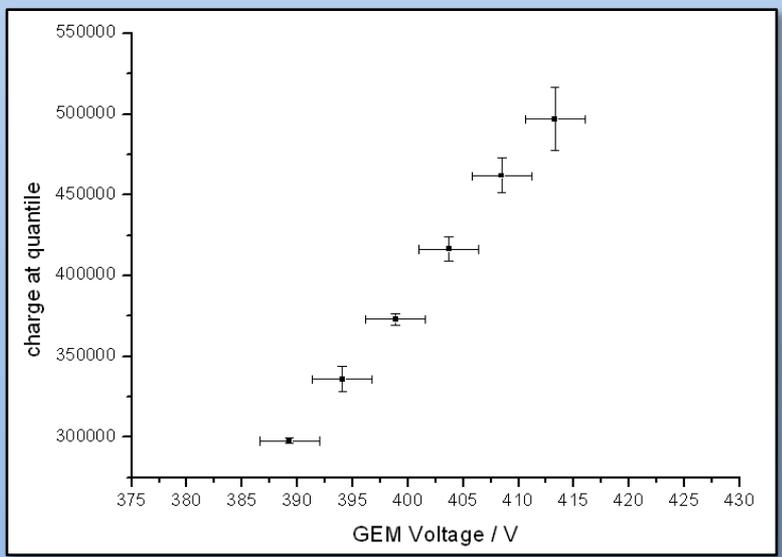
Comparison: 2x2 with a rebinned 1x1

Is there a amount of charge pixels start cross-talking?

ratio of cross-talking clusters in real data
with
corresponding (upper) quantile of rebinned 1x1



1x1 chip
rebinned to 2x2
Volt./GEM: 415V



→ charge at quantile should be constant
assuming a critical charge at which passivated
pixels start showing a signal

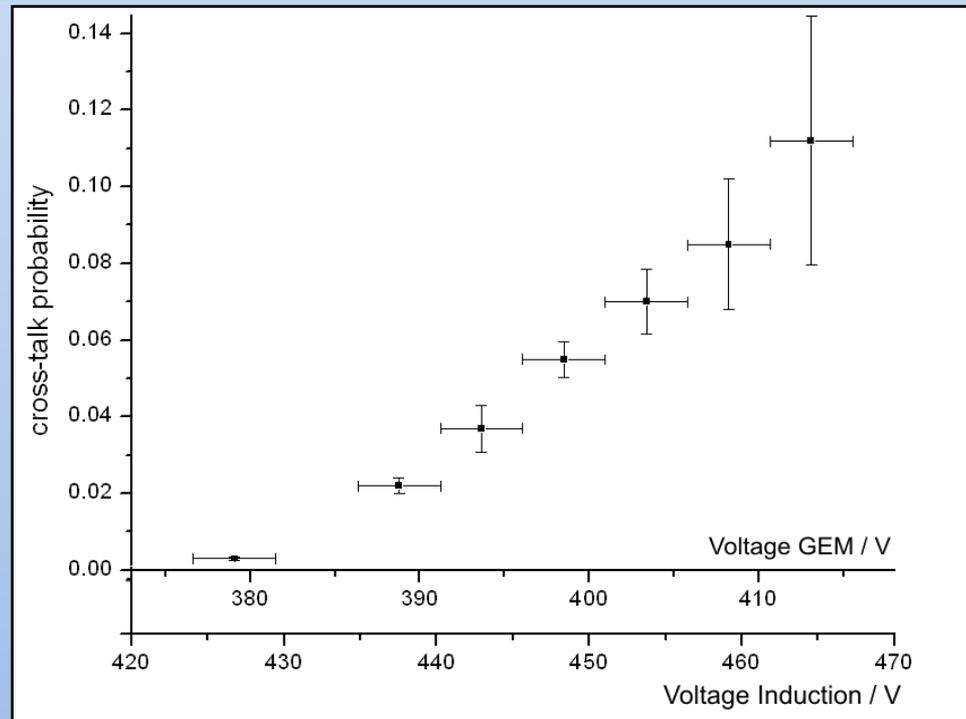
Passivated pixel cross-talk

Examine:

ratio of cross-talking clusters
vs.
applied applied voltage

Effect:

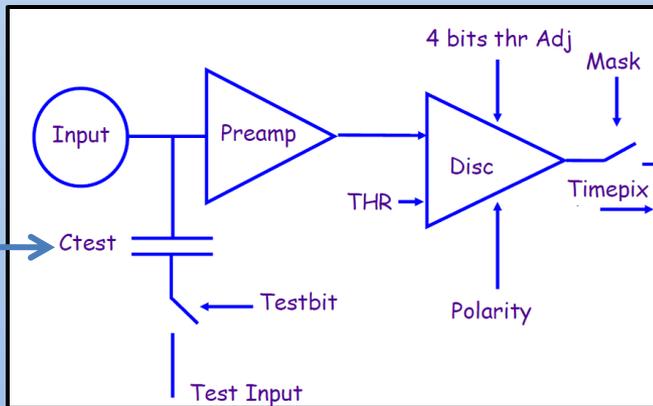
cross-talk probability depends on E-Field strength
(not only on the amount of charge)



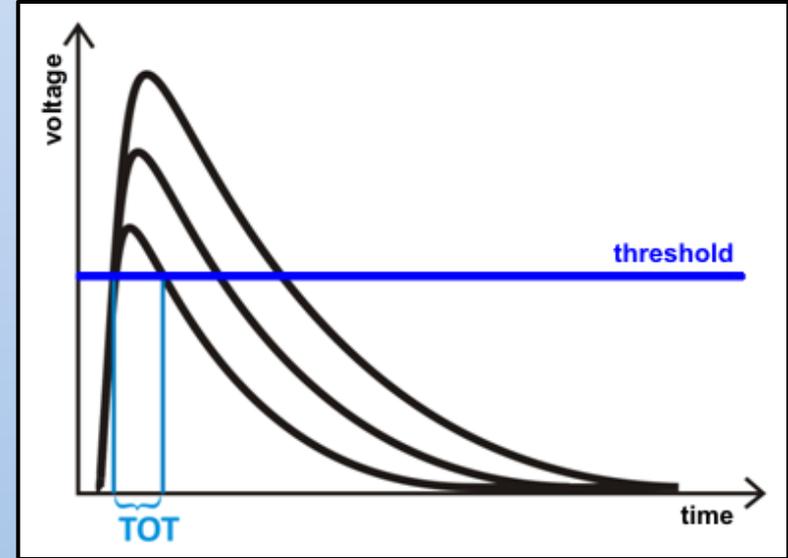
Pixel calibration

Procedure:

- test pulse at test capacity C_{test} (ca. 8 fF)
→ injected charge on pixel



(TimePix manual)



scheme: charge-/ discharge curve C_{test}

Interfaces

Measurements : 40 Mhz

USB

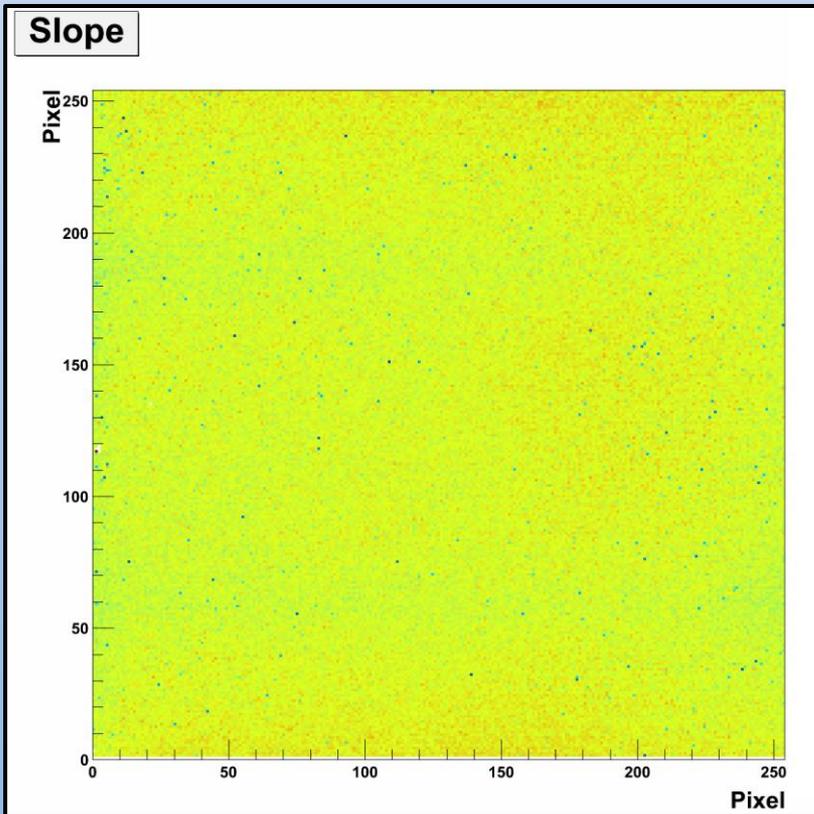


MUROS

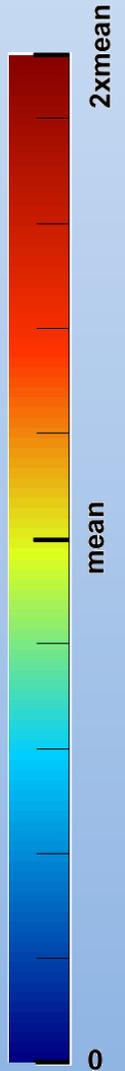
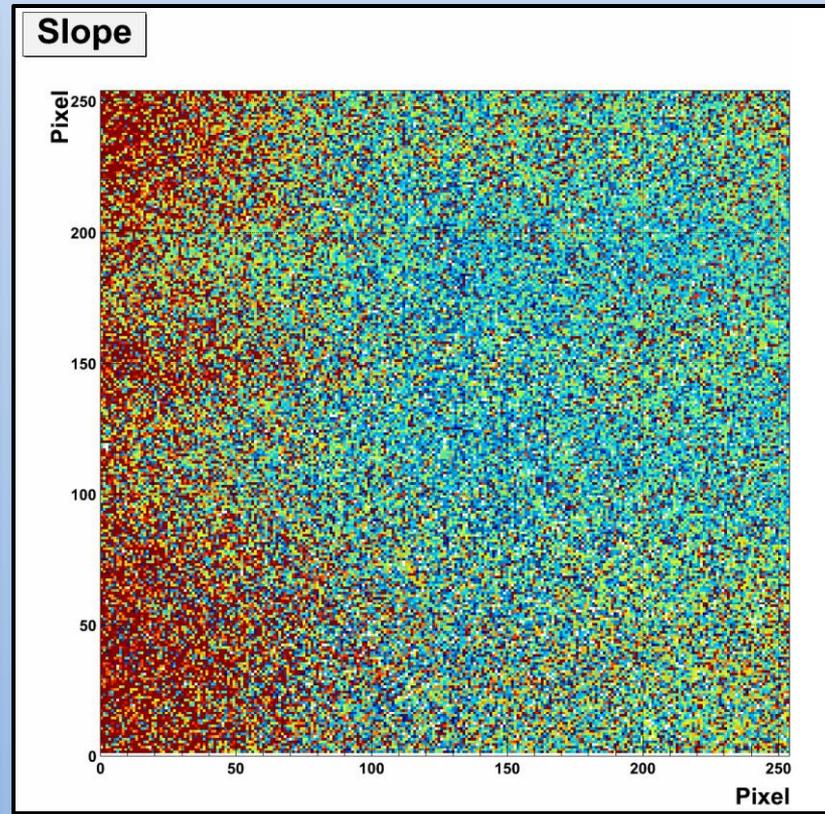


MUROS vs. USB

MUROS



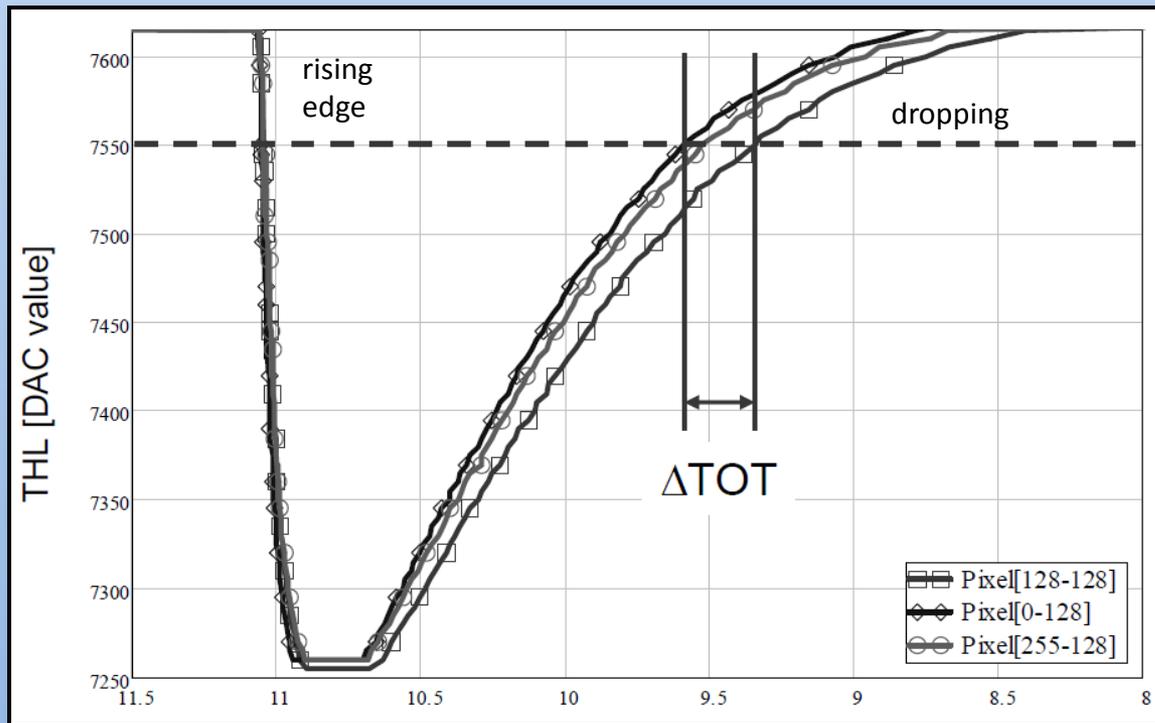
USB



USB Interface_(1.2.2): calibration with test pulses not possible

Problem

- current in discharging flank varies from pixel to pixel
→ variation in TOT

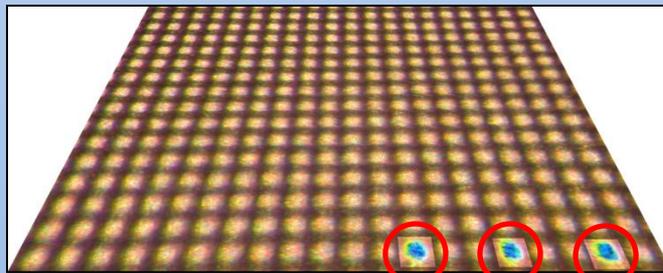


Until now: calibration *chipwise* (mean over all pixel)

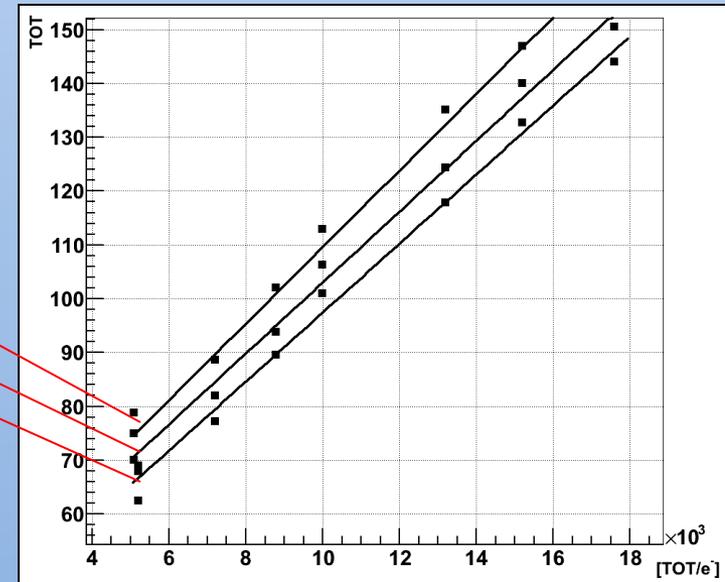
- TOT counts depend linearly on the deposited charge

$$\text{TOT} = b \cdot Q + a$$

→ every pixel has its own response function

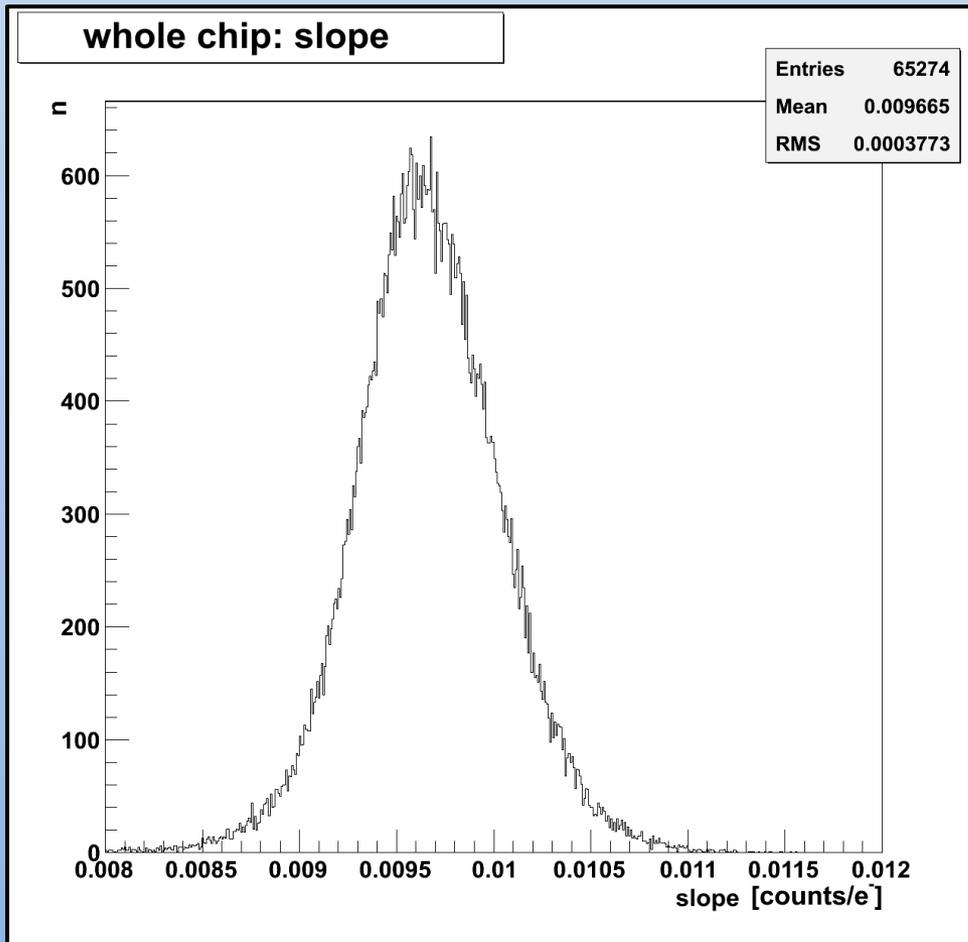


(Detail TimePix)



Will a pixelwise calibration improve the charge calibration?

Distribution of slopes (Muros)



variation of all slopes: 4%
relative error on individual pixel slope fits: 3%

Under assumption of a convolution of
the given distribution of the pixels
with a gauss curve (fit error):

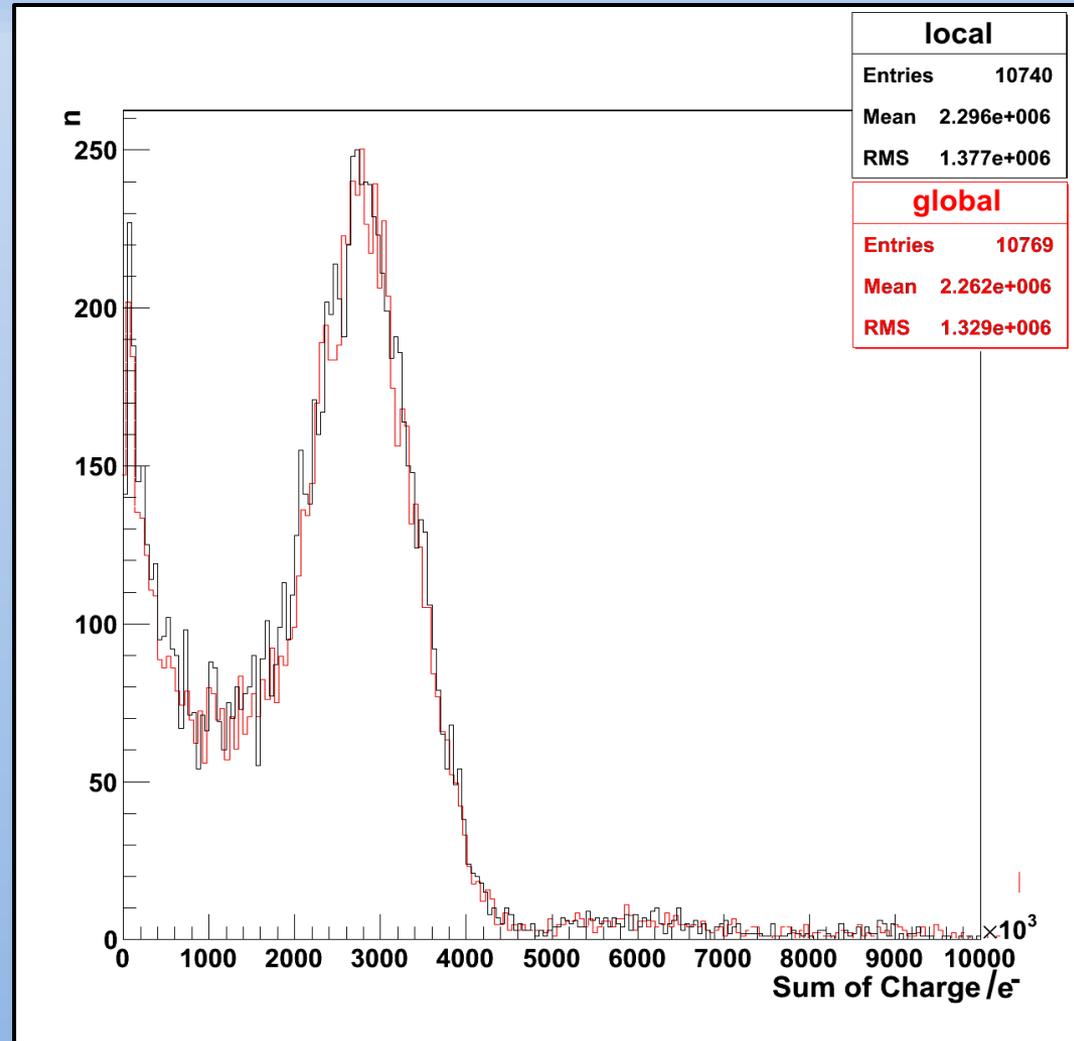
→ variation of slopes ca. 2%

calibration with higher precision necessary

data: 1x1 metallized

reconstructed clusters with
global (same scaling for all pixels)
and **local charge calibration**

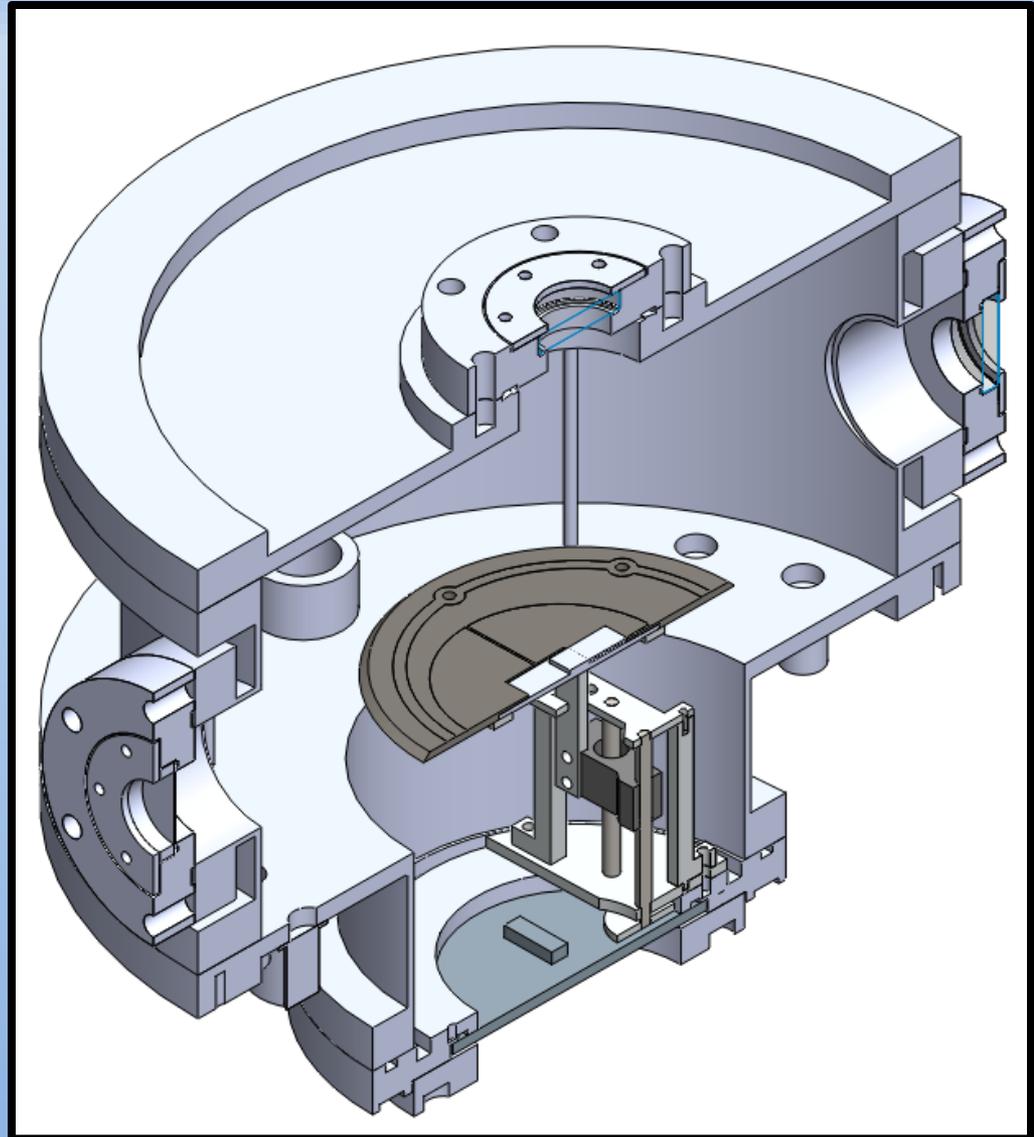
→ *Shape* of cluster-TOT spectrum
is not changed by charge calibration



data: 1x1 metallized
GEM voltage 375 V

Goals

- modular construction
- non magnetic materials
- gas-tight
- GEM (mit 12x12 cm²) incl.
 - readout electronics
 - HV
- experiments with:
 - N₂-laser
 - testbeam
 - radioaktive source
- simple exchange of TimePix chips



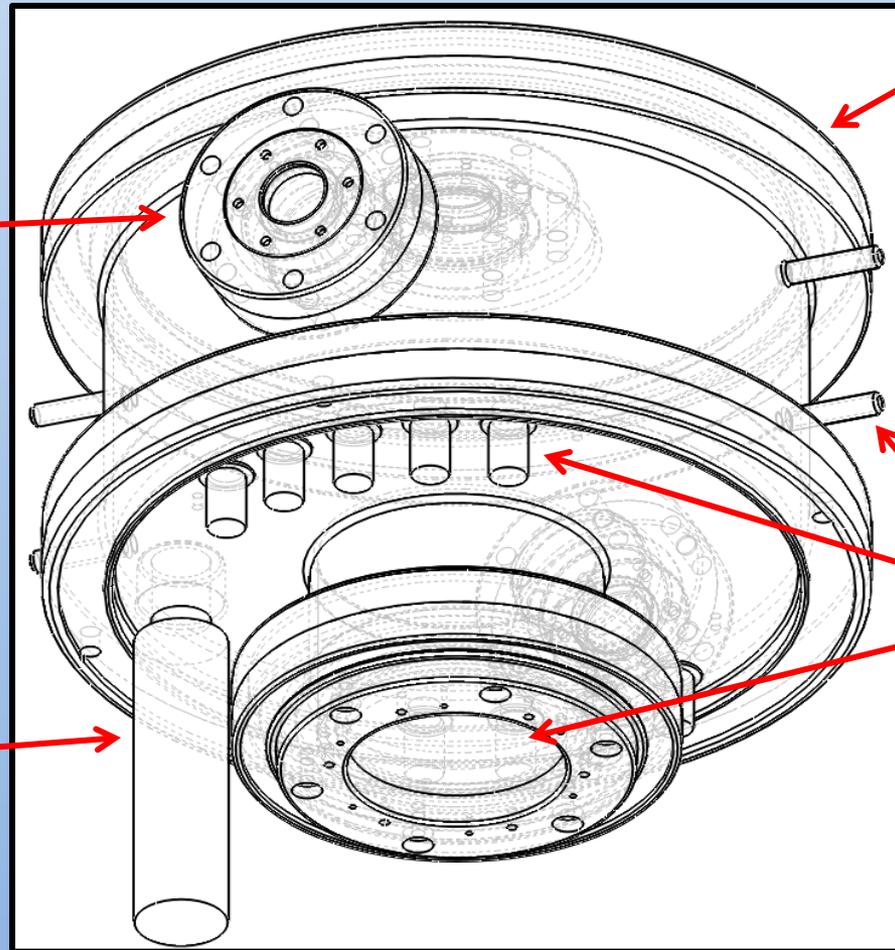
test chamber for gaseous detectors with max. 12x12 cm²

windows:

- optical [plexiglas]
- laser [quarz]
- testbeam [Al]

sensors:

- pressure (+/- 0,5 mbar)
- temperatur e(+/- 0,5 K)
- (humidity)



Iso-K system

connections:

- gas in- /outlets
- SHV plugs (GEM)
- elektronik (board)



- pixel enlargement reduces necessary gain
- cross-talking (at high voltages) does not depend on deposited charge
- pixelwise calibration could improve charge reconstruction
- USB-interface(1.2.2) should not be used for calibration
- a new test chamber has been developed



- more studies in calibration with test pulses
- comparison of postprocessed chips ($n \times n$)
in respect to:
 - gas amplification
 - spatial resolution
 - detection efficiency

The TimePix chip 2006

A modified MediPix2 Chip for TPC applications

Motivation:

knowing the time of arrival of avalanches at pixels

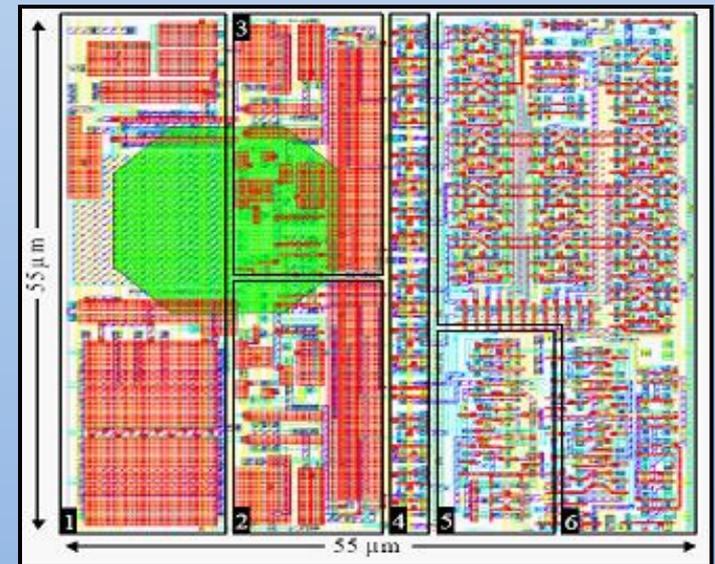
⇒ use 14bits counter not for counting the #hits, but for counting clock cycles

- (only lower threshold)
- clock up to 100 MHz in each pixel
- threshold (whole chip): $\approx 700 e^-$
- 4 different modes possible

modes definable for every pixel
using a “map”

TPC-Setup:

- use Time-arrival mode
- use TOT for calculating charge



TimePix chip with active area (green)

The TimePix chip 2006

TimePix Modes

